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Intel Foundry Gathers Customers and Partners, Outlines Priorities

At Direct Connect, Intel Foundry shares process technology roadmap, advanced packaging momentum and ecosystem partnerships.

SAN JOSE, Calif.--(BUSINESS WIRE)-- Today at Intel Foundry Direct Connect, the company will share progress on multiple generations of its core process and advanced packaging technologies. The company will also announce new ecosystem programs and partnerships, and welcome industry leaders to discuss how a systems foundry approach enables collaboration with partners and unlocks innovation for customers.

This press release features multimedia. View the full release here: https://www.businesswire.com/news/home/20250429362195/en/

An Intel Foundry engineer in clean room gear holds a silicon wafer at an Intel manufacturing facility in Chandler, Arizona. (Credit: Intel Foundry)

Intel CEO Lip-Bu Tan will open the event by discussing Intel Foundry's progress and priorities as the company drives the next phase of its foundry strategy. Naga Chandrasekaran, Intel Foundry chief technology and operations officer, and Kevin O'Buckley, general manager of Foundry Services, will also deliver keynotes during the morning session, sharing process and advanced packaging news while highlighting Intel Foundry's globally diverse manufacturing and supply chain.

Tan will be joined on stage by ecosystem partners including Synopsys, Cadence, Siemens EDA and PDF Solutions to highlight collaboration in serving foundry customers. O'Buckley will be joined by executives from MediaTek, Microsoft and Qualcomm.

"Intel is committed to building a world-class foundry that serves the growing need for leading-edge process technology, advanced packaging and manufacturing," said Tan. "Our No. 1 job is to listen to our customers and earn their trust by creating solutions to enable their success. The work we are doing to drive an engineering-first culture across Intel while strengthening our partnerships throughout the foundry ecosystem will help us to advance our strategy, improve our execution and win in the market long term."

Event Press Kit: Intel Foundry Direct Connect 2025

Today's announcements encompass core process and advanced packaging technology, a milestone in domestic U.S. manufacturing, and ecosystem support required to earn the trust of foundry customers. They include:

Process Technology

- Intel Foundry has engaged with lead customers on the Intel 14A process technology, the successor to Intel 18A. The company has distributed to lead customers an early version of the Intel 14A Process Design Kit (PDK), and multiple customers have expressed their intent to build test chips on the new process node.
- Intel 14A will feature PowerDirect direct contact power delivery, building on the PowerVia backside power delivery technology in Intel 18A.
- Intel 18A is now in risk production and expected to reach volume manufacturing this year. Intel Foundry's ecosystem partners have electronic design automation (EDA) enablement, reference flows and intellectual property (IP) ready for production designs today.
- The new Intel 18A variant, called Intel 18A-P, is designed to deliver enhanced performance to a broader set of foundry customers. Early wafers based on Intel 18A-P are in the fab now. Because Intel 18A-P will be design rule-compatible with Intel 18A, IP and EDA partners have already started updating their offerings for the variant.
- Intel 18A-PT is another new variant that builds on Intel 18A-P performance and power efficiency advancements. Intel 18A-PT can be connected to top die using Foveros Direct 3D with hybrid bonding interconnect pitch less than 5 micrometers (µm).
- Intel Foundry's first production 16 nanometer (nm) tape-out is in the fab now, and the company is engaging with lead customers on a 12nm node and derivatives built in collaboration with UMC.

Learn more about Intel Foundry process technology.

Advanced Packaging

- Intel Foundry offers system-level integration using Intel 14A on Intel 18A-PT, connected via Foveros Direct (3D stacking) and embedded multi-die interconnect bridging (2.5D bridging).
- New advanced packaging technology offerings include EMIB-T to enable future high bandwidth memory needs and two new additions to the Foveros architecture: Foveros-R and Foveros-B provide additional efficient and flexible options for customers.
- A new engagement with Amkor Technology increases customer flexibility in choosing the right advanced packaging technology for their needs.

Learn more about Intel Foundry advanced packaging and test technology.

Manufacturing

- Fab 52 in Arizona has successfully "run the lot," marking the first wafer processed through the facility, demonstrating progress in domestic manufacturing of leading-edge Intel 18A wafers. Intel 18A volume production will begin in Intel's Oregon fabs as Arizona manufacturing ramps later this year. Intel 18A and Intel 14A research, development and wafer production will all be U.S.-based.

Learn more about Intel Foundry manufacturing capabilities.

Ecosystem

- New programs have been added within Intel Foundry's Accelerator Alliance – Intel Foundry Chiplet Alliance and Value Chain Alliance – along with a range of

announcements from top ecosystem partners.

Learn more about Intel Foundry ecosystem alliances.

Delivering Trusted Ecosystem Tools and IP

Intel Foundry is supported by a comprehensive portfolio of IP, EDA and design services solutions delivered by trusted, proven ecosystem partners to drive advancements beyond traditional node scaling. As the newest program in Intel Foundry's Accelerator Alliance, the new Intel Foundry Chiplet Alliance will initially focus on defining and driving infrastructure on advanced technology for government applications and key commercial markets. The Intel Foundry Chiplet Alliance will provide an assured and scalable path for customers looking to deploy designs that leverage interoperable and secure chiplet solutions for targeted applications and markets.

The Intel Foundry Accelerator Alliance also includes IP Alliance, EDA Alliance, Design Services Alliance, Cloud Alliance and USMAG Alliance.

Forward-Looking Statements

This release contains forward-looking statements that involve a number of risks and uncertainties, including with respect to our business plans and strategy and anticipated benefits therefrom, our fabrication process technology roadmap, our advanced packaging roadmap, our manufacturing facilities, and our ecosystem alliances, tools and IP. Such statements involve many risks and uncertainties that could cause our actual results to differ materially from those expressed or implied, including those associated with:

- the high level of competition and rapid technological change in our industry;
- the significant long-term and inherently risky investments we are making in R&D and manufacturing facilities that may not realize a favorable return;
- the complexities and uncertainties in developing and implementing new semiconductor products and manufacturing process technologies;
- our ability to time and scale our capital investments appropriately and successfully secure favorable alternative financing arrangements and government grants;
- implementing new business strategies and investing in new businesses and technologies;
- changes in demand for our products;
- macroeconomic conditions and geopolitical tensions and conflicts, including geopolitical and trade tensions between the U.S. and China, the impacts of Russia's war on Ukraine, tensions and conflict affecting Israel and the Middle East, and rising tensions between mainland China and Taiwan;
- the evolving market for products with AI capabilities;
- our complex global supply chain, including from disruptions, delays, trade tensions and conflicts, or shortages;
- recently elevated geopolitical tensions, volatility and uncertainty with respect to international trade policies, including tariffs and export controls, impacting our business, the markets in which we compete and the world economy;
- product defects, errata and other product issues, particularly as we develop next-generation products and implement next-generation manufacturing process technologies;

- potential security vulnerabilities in our products;
- increasing and evolving cybersecurity threats and privacy risks;
- IP risks including related litigation and regulatory proceedings;
- the need to attract, retain and motivate key talent;
- strategic transactions and investments;
- sales-related risks, including customer concentration and the use of distributors and other third parties;
- our significantly reduced return of capital in recent years;
- our debt obligations and our ability to access sources of capital;
- complex and evolving laws and regulations across many jurisdictions;
- fluctuations in currency exchange rates;
- changes in our effective tax rate;
- catastrophic events;
- environmental, health, safety and product regulations;
- our initiatives and new legal requirements with respect to corporate responsibility matters; and
- other risks and uncertainties described in this release, our 2024 Form 10-K, our Q1 2025 Form 10-Q, and our other filings with the SEC.

Given these risks and uncertainties, readers are cautioned not to place undue reliance on such forward-looking statements. Readers are urged to carefully review and consider the various disclosures made in this release and in other documents we file from time to time with the SEC that disclose risks and uncertainties that may affect our business.

Unless specifically indicated otherwise, the forward-looking statements in this release do not reflect the potential impact of any divestitures, mergers, acquisitions, or other business combinations that have not been completed as of the date of this filing. In addition, the forward-looking statements in this release are based on management's expectations as of the date of this release, unless an earlier date is specified, including expectations based on third-party information and projections that management believes to be reputable. We do not undertake, and expressly disclaim any duty, to update such statements, whether as a result of new information, new developments, or otherwise, except to the extent that disclosure may be required by law.

About Intel Foundry

Intel Foundry is a full-service systems foundry dedicated to delivering leading-edge silicon process and advanced packaging technology. We provide an unparalleled blend of industry-leading technology with a rich IP portfolio, a world-class design ecosystem, and an operationally resilient global manufacturing supply chain. For further information, visit www.intel.com/foundry.

About Intel

Intel (Nasdaq: INTC) is an industry leader, creating world-changing technology that enables global progress and enriches lives. Inspired by Moore’s Law, we continuously work to advance the design and manufacturing of semiconductors to help address our customers’ greatest challenges. By embedding intelligence in the cloud, network, edge and every kind of computing device, we unleash the potential of data to transform business and society for the better. To learn more about Intel’s innovations, go to newsroom.intel.com and intel.com.

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